

FL1002
No Clean Liquid Flux

Product Description

Asahi FL1002 non-activated rosin fluxes are used for applications where active flux is not permitted and critical electronic assemblies are involved. It is very reliable and highly recommended for solderability testing of leads, printed circuit boards and other electrical components because of their consistently high quality. FL1002 is specially formulated so that the flux effectively removes the oxides and provides a thick flux coating to the boards from heat damage.

Application

FL1002 is specially formulated for dipping in solderability test application. Recommended on-board preheat temperature is 90 – 110 °C.

Residue Removal

Since the residues are minimal and non-corrosive, removal is usually not required. If cleaning is required, the flux residue could be removed by any solvent or aqueous flux cleaner available in the market.

Recommended Solvent

Asahi's complementary Solvent #2000. Solvent can be stored for about 2 years under normal storage conditions of 25°C.

Health and Safety

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

Storage

Under proper storage condition, FL1002 can be stored for up to 6 months. FL1002 is flammable. Keep away from all sources of heat, sparks, flame and sunlight.

Packaging

Available in 18kg/carboy.

Specification

Item	Result
State	Liquid
Colour	Yellow
Specific Gravity @ 25°C	0.846 +/- 0.005
<small>JIS Z 3197 8.2.2</small>	
Non-volatile Solid Content (110°C, 1hr)	25.0 +/- 1.0 wt%
<small>IPC-TM-650 2.3.34</small>	
<small>JIS Z 3197 8.1.3</small>	
Halide Content	Not added
<small>JIS Z 3197 8.1.4.2.1</small>	
Silver Chromate Test	Halide may not be present
<small>IPC-TM-650 2.3.33</small>	
<small>JIS Z 3197 8.1.4.2.3</small>	
Surface Insulation Resistance (85°C, 85%RH, 1000hrs)	> 1 x 10 ⁸ Ω, Pass
<small>IPC-TM-650 2.6.3.3</small>	
Copper Corrosion Test	Pass
<small>IPC-TM-650 2.6.15</small>	
<small>JIS Z 3197 8.4.1</small>	
Copper Mirror Test	Classified as "L", Pass
<small>IPC-TM-650 2.3.32</small>	
<small>JIS Z 3197 8.4.2</small>	
Flux Activity Classification	ROLO
<small>IPC J-STD-004</small>	
Residue Dryness Test	Dry
<small>IPC-TM-650 2.4.47</small>	
<small>JIS Z 3197 8.5.1</small>	

DISCLAIMER OF LIABILITY

"All statements, information and recommendations contained in this catalog are based on data and test results which we consider, to the best of our knowledge and belief, to be reliable and informative to the users but the accuracy and completeness thereof is not guaranteed. No warranty, expressed or implied, statutory or otherwise, is given regarding the use of the information and products contained in this catalog since the conditions and suitability for use, handlings, storage or possession of the products are determined by the users and are therefore beyond our control. We shall not be liable in respect of any liabilities, losses (including consequential losses), damages, proceedings, costs, claims or injuries whatsoever sustained or suffered by the users (including any third parties) in connection with the use of the information, recommendation and the products contained in this catalog."

Singapore Asahi Chemical and Solder Industries Pte Ltd

47 Pandan Road Singapore 609288

Tel: +65 6262-1616 Fax: +65 6261-6311

 Website: <http://www.asahisolder.com> Email: enquiry@sinasahi.com.sg